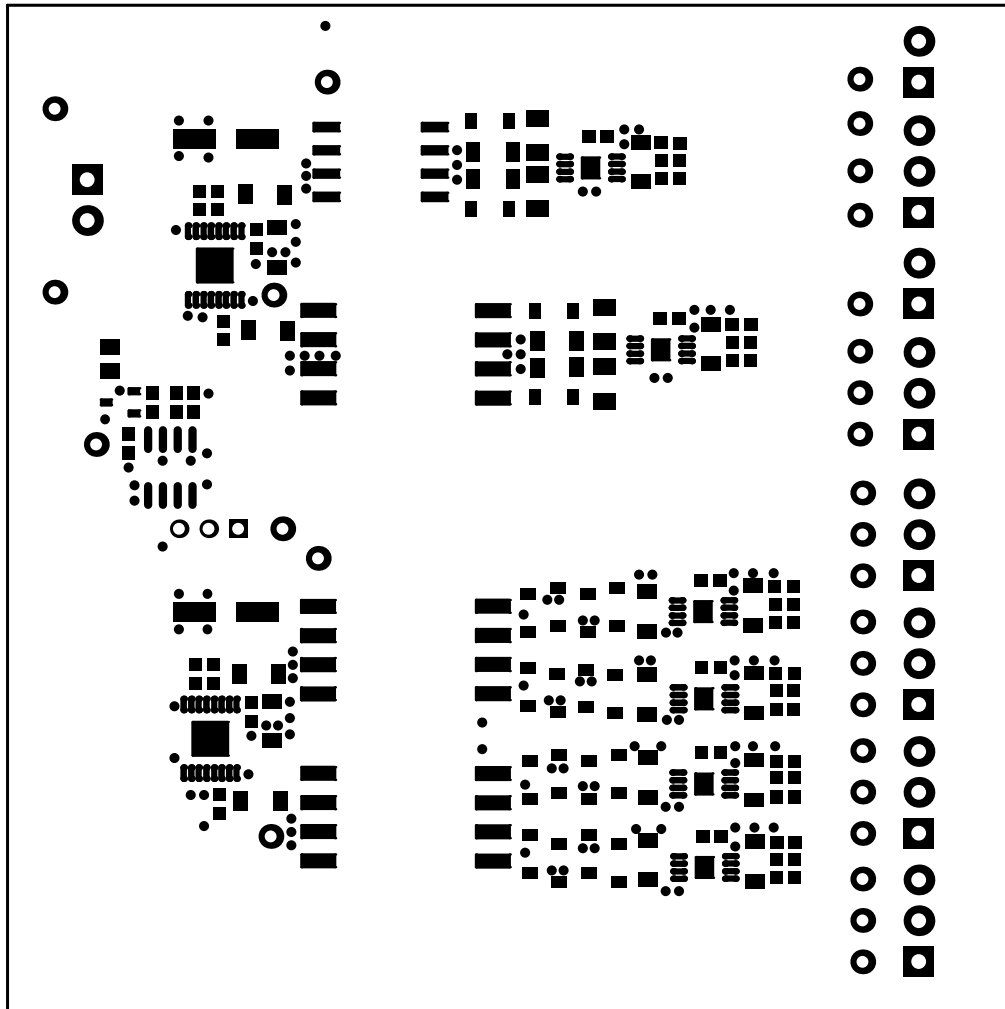
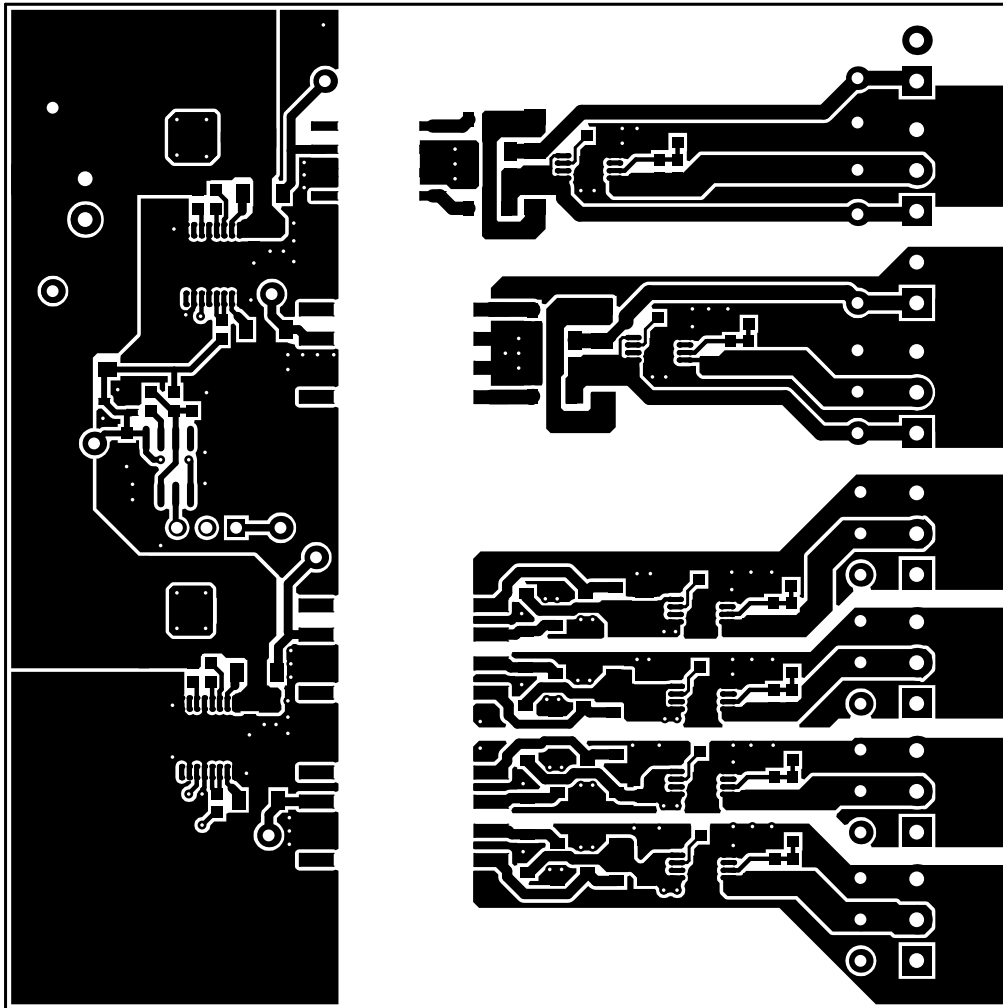


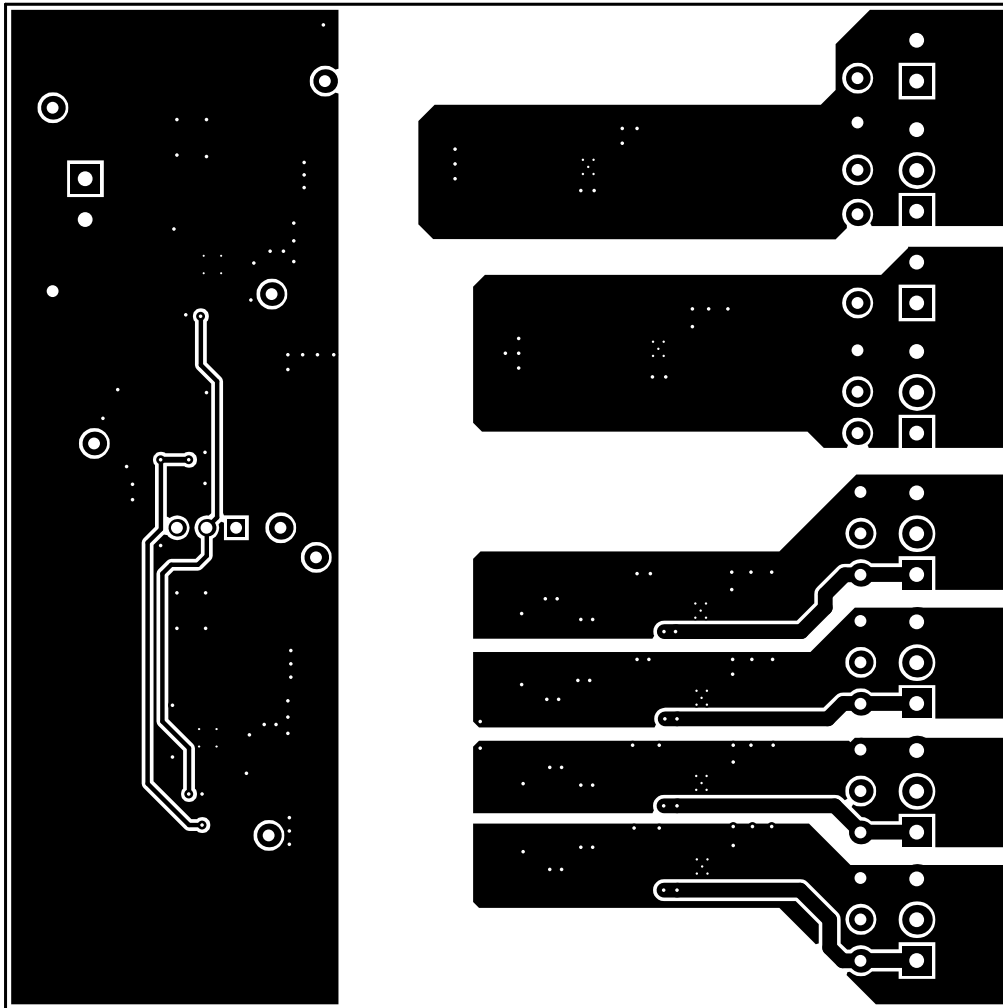
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP11373	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #:		
PLOT NAME = Top Overlay	GENERATED : 11/6/2015	1:32:45 PM	TEXAS INSTRUMENTS



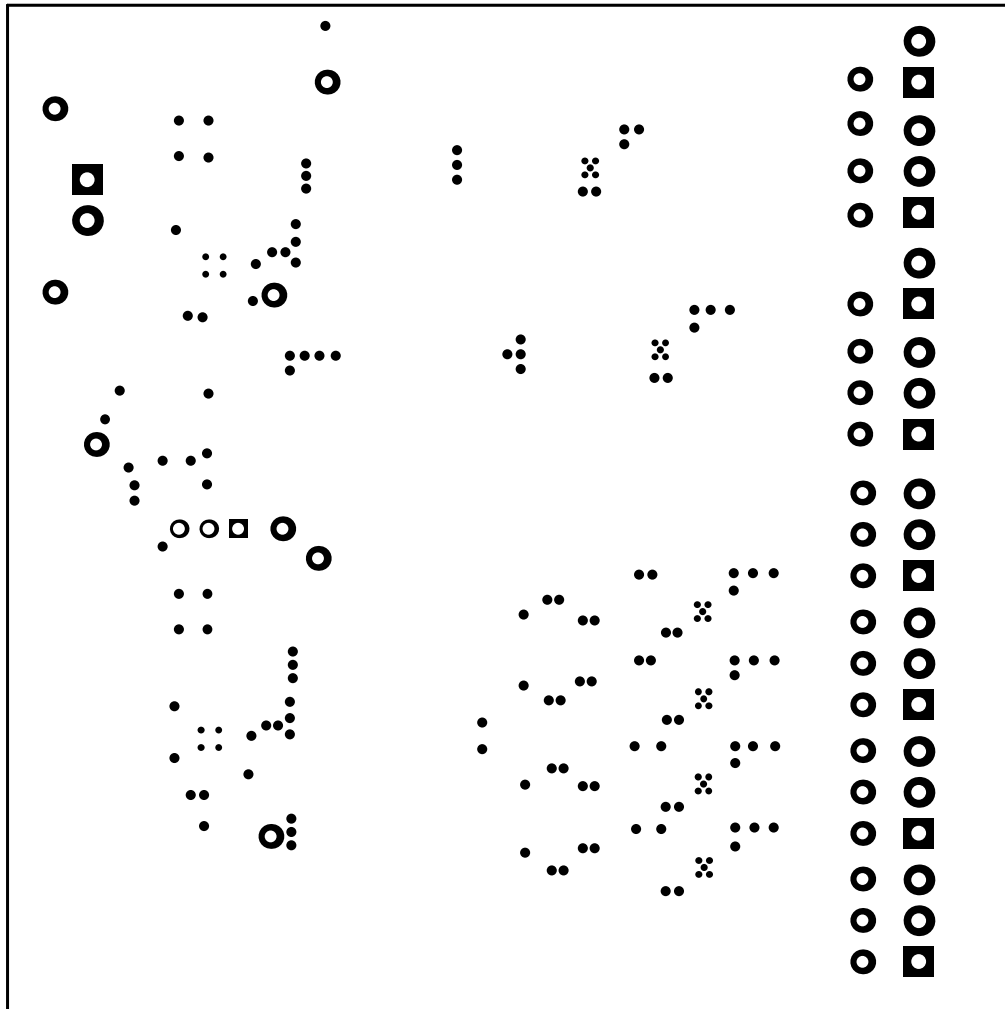
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP11373	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #:		
PLOT NAME = Top Solder Mask	GENERATED : 11/6/2015	1:32:46 PM	TEXAS INSTRUMENTS



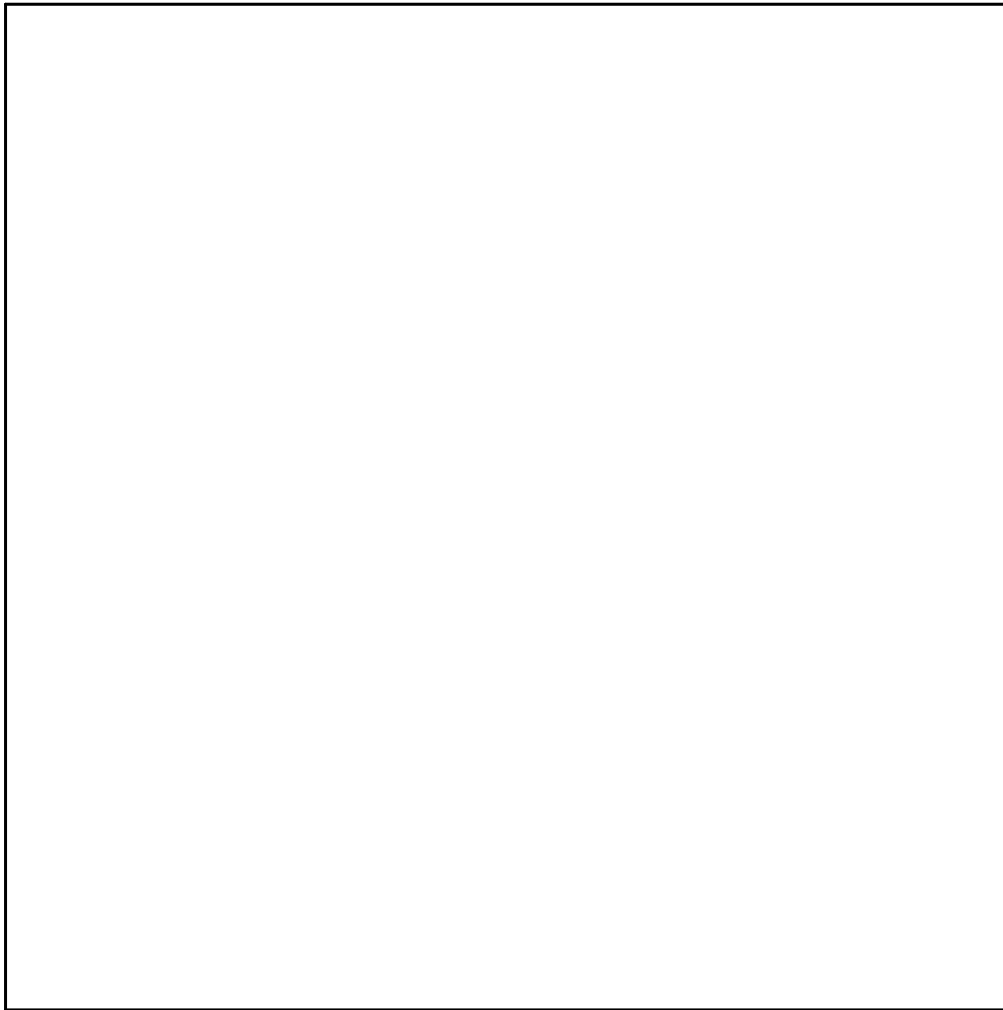
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP11373	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #:		
PLOT NAME = Top Layer	GENERATED : 11/6/2015	1:32:47 PM	TEXAS INSTRUMENTS



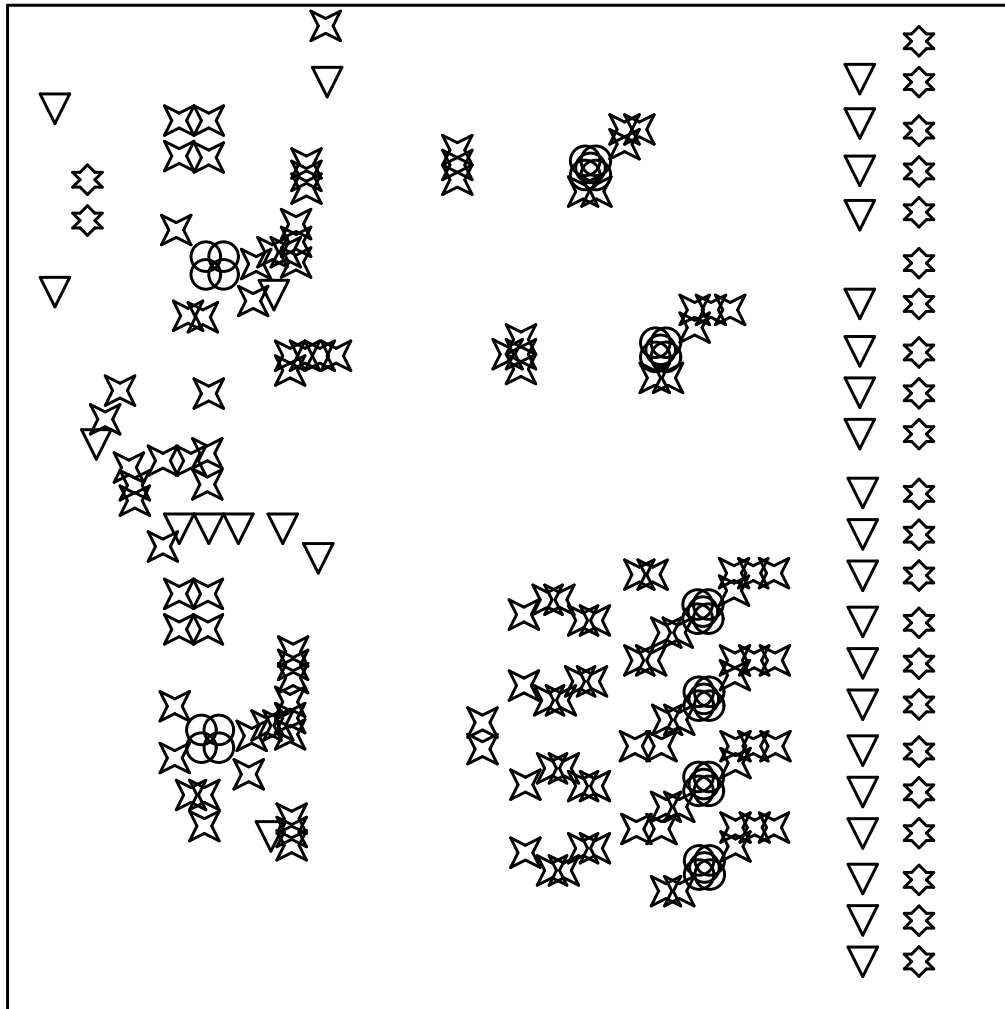
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP11373	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #:		
PLOT NAME = Bottom Layer	GENERATED : 11/6/2015	1:32:47 PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP11373	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #:		
PLOT NAME = Bottom Solder Mask	GENERATED : 11/6/2015	1:32:48 PM	TEXAS INSTRUMENTS

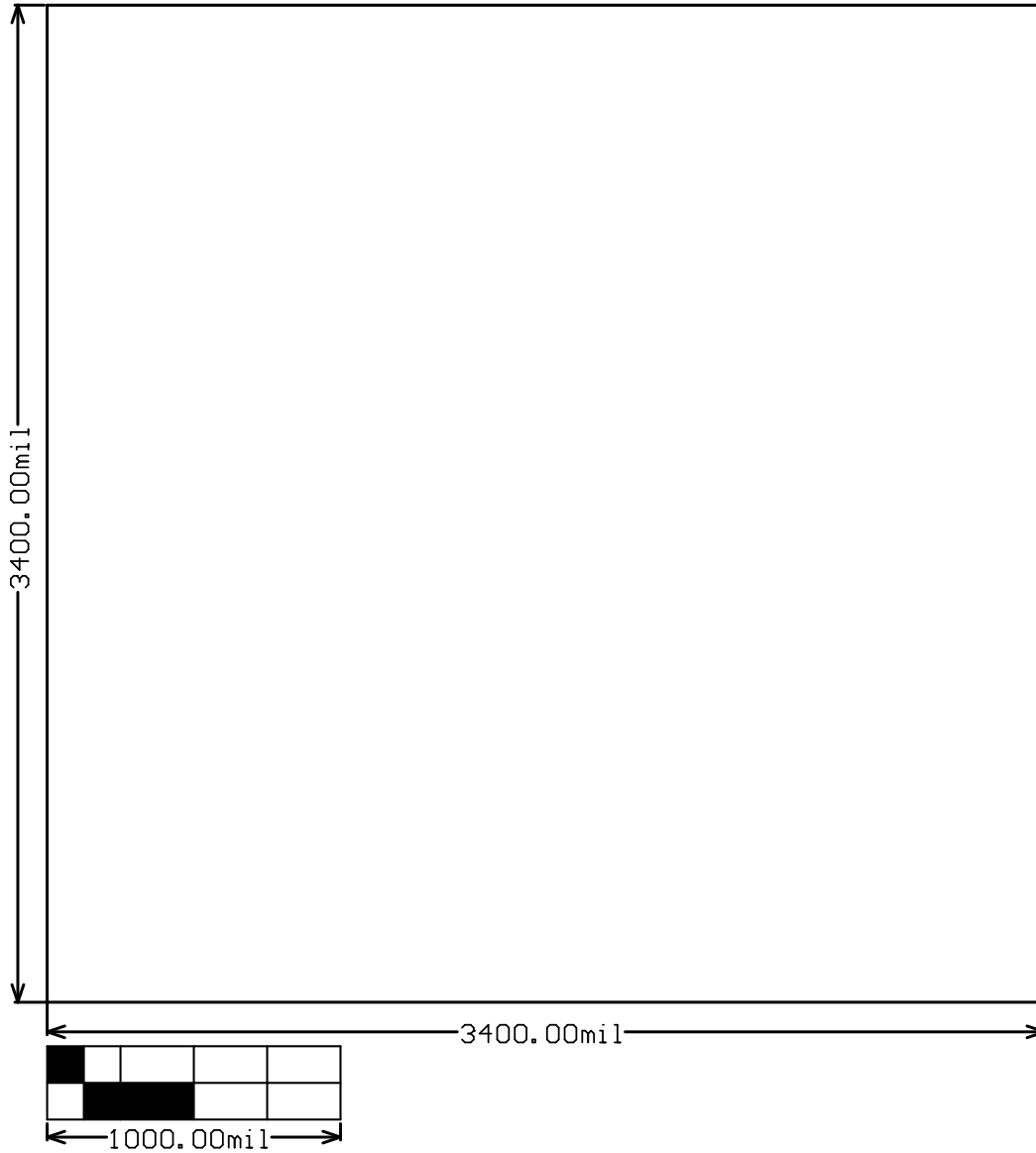


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP11373	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #:		
PLOT NAME = Bottom Overlay	GENERATED : 11/6/2015 1:32:49 PM	TEXAS INSTRUMENTS	



Symbol	Quantity	Finished Hole Size	Plated	Hole Type
○	38	7.87mil (0.200mm)	PTH	Round
✕	128	12.00mil (0.305mm)	PTH	Round
▽	31	40.00mil (1.016mm)	PTH	Round
☆	24	50.00mil (1.270mm)	PTH	Round
	221 Total			

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP11373	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #:		
PLOT NAME = Drill Drawing	GENERATED : 11/6/2015	1:32:50 PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP11373	REV: A	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #:		
PLOT NAME = Board Dimensions	GENERATED : 11/6/2015 1:32:51 PM	TEXAS INSTRUMENTS	

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